

Chip Bead For EMI Suppression

CIS10P Series (1608/ EIA 0603)



APPLICATION

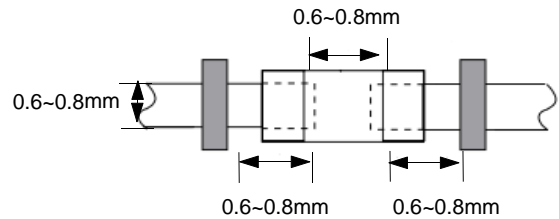
Noise Suppression in power line

FEATURES

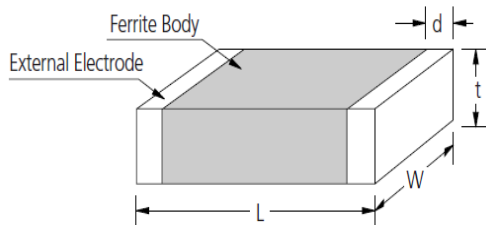
Smallest beads used in high current.

- CIS series is used for high current. (~ 6A)

RECOMMENDED LAND PATTERN



DIMENSION

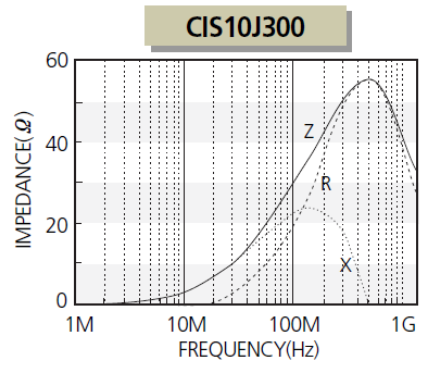
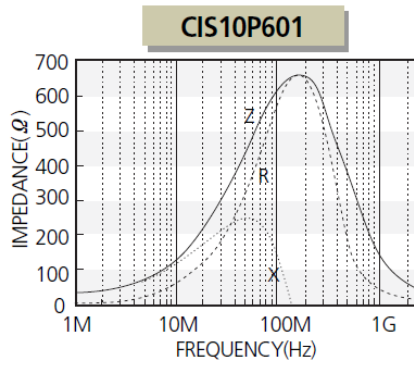
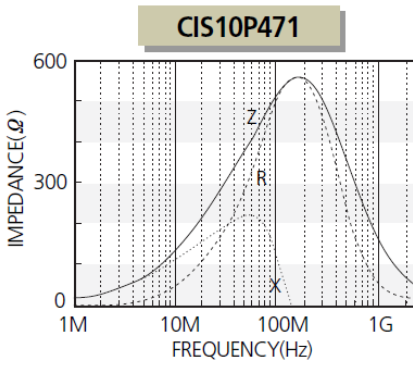
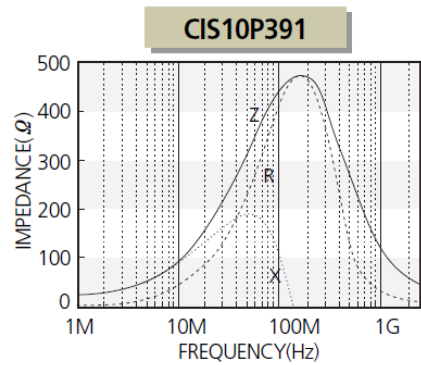
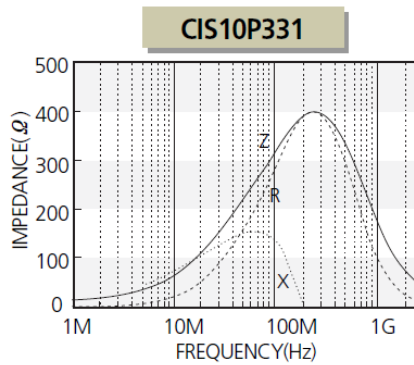
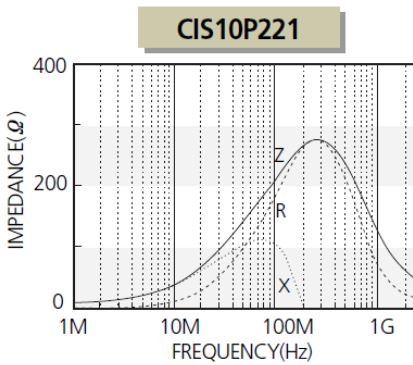
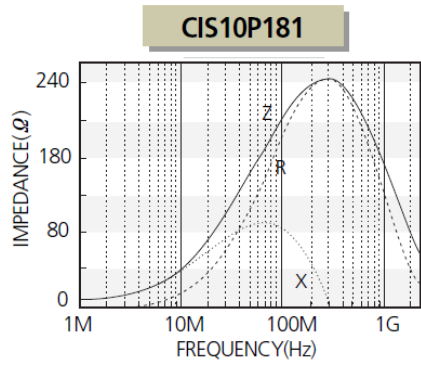
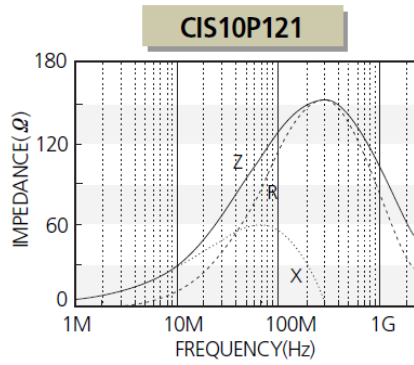
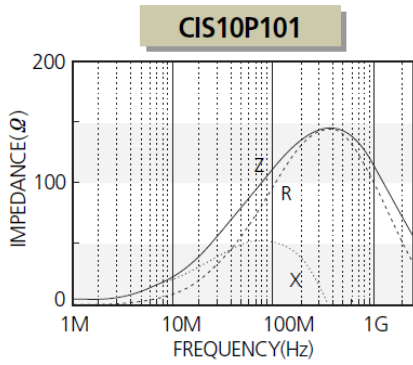
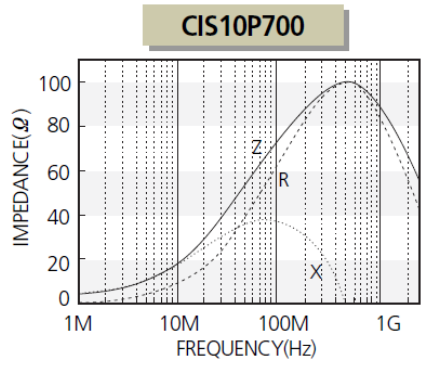
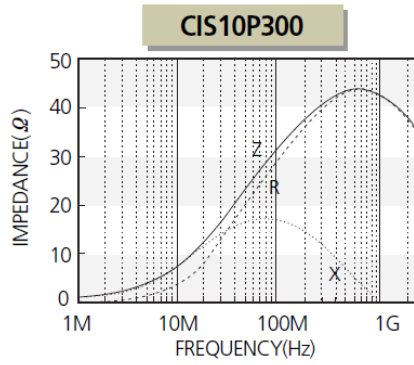
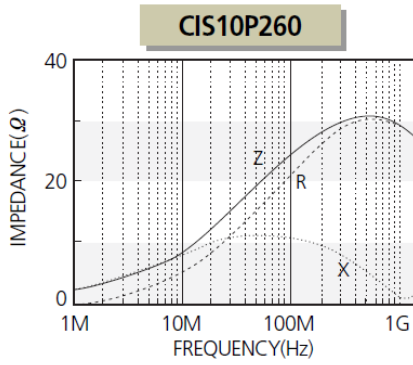


Type	Dimension [mm]			
	L	W	t	d
10	1.6 ±0.15	0.8 ±0.15	0.6±0.15, 0.8±0.15	0.3 ±0.2

DESCRIPTION

Part No.	Thickness (mm)	Impedance (Ω)±25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIS10P260AC	0.6±0.15	26	0.007	6000
CIS10P300AC	0.6±0.15	30	0.01	6000
CIS10P700AC	0.6±0.15	70	0.02	4000
CIS10P101AC	0.6±0.15	100	0.03	3000
CIS10P121AC	0.6±0.15	120	0.03	3000
CIS10P181AC	0.6±0.15	180	0.04	2500
CIS10P221NC	0.8±0.15	220	0.05	2500
CIS10P301NC	0.8±0.15	300	0.07	2000
CIS10P331NC	0.8±0.15	330	0.07	1700
CIS10P391NC	0.8±0.15	390	0.10	1200
CIS10P471NC	0.8±0.15	470	0.13	1500
CIS10P601NC	0.8±0.15	600	0.15	1300

CHARACTERISTIC DATA



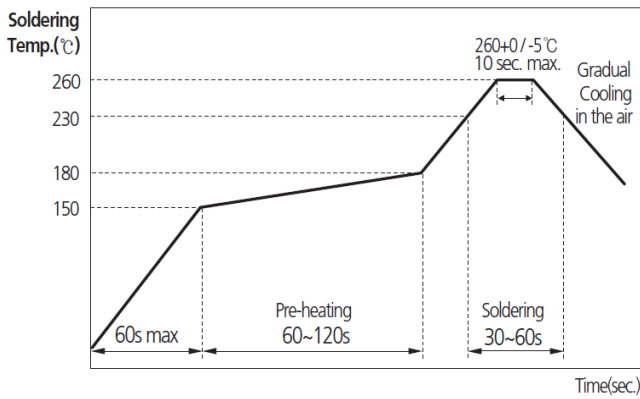
PRODUCT IDENTIFICATION

CI S 10 P 300 A C
(1) (2) (3) (4) (5) (6) (7)

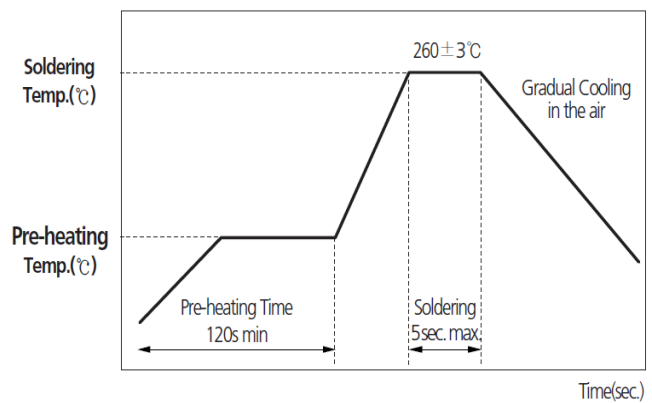
- (1) Chip Beads
- (2) Ultra high current (~6A)
- (3) Dimension
- (4) Material Code
- (5) Nominal impedance (300:30Ω, 121:120Ω)
- (6) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (7) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Card Board Taping	4000

■ NOTICE :All specifications are subject to change without previous notice. Please contact with product representatives or engineers to check specifications.

单击下面可查看定价，库存，交付和生命周期等信息

[>>Samsung Electro-Mechanics\(三星电机\)](#)